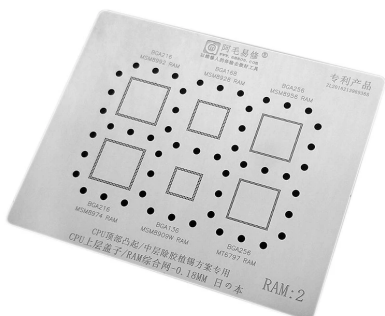


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BGA Reballing Stencil for BGA RAM.2 CPU UP 0.18mm

Product ID: 22761

Price: **11.00 EUR**

Product weight: **0.50 kg**

Description:

BGA Reballing Stencil for BGA RAM.2 CPU UP 0.18mm stencil for: BGA216 MSM8992 RAM; BGA168 MSM8928 RAM; BGA256 MSM8956 RAM; BGA216 MSM8974RAM; BGA136 MSM8909W RAM; BGA256 MT6797 RAM.

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